

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Han-Chee Yen</td> <td>05/03/2012</td> </tr> <tr> <td>Chi-Sheng Chung</td> <td>04/27/2012</td> </tr> <tr> <td>Kuo-Hsien Liao</td> <td>04/27/2012</td> </tr> <tr> <td>Yung-I Yeh</td> <td>04/27/2012</td> </tr> </tbody> </table>	Name	Execution Date	Han-Chee Yen	05/03/2012	Chi-Sheng Chung	04/27/2012	Kuo-Hsien Liao	04/27/2012	Yung-I Yeh	04/27/2012	
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Kuo-Hsien Liao	04/27/2012										
Yung-I Yeh	04/27/2012										
RECEIVING PARTY DATA											
Name:	Advanced Semiconductor Engineering, Inc.										
Street Address:	No. 26, Chin 3rd Road, Nantze Export Processing Zone										
City:	Kaohsiung										
State/Country:	TAIWAN										
Postal Code:	811										
PROPERTY NUMBERS Total: 1											
Property Type	Number										
Application Number:	13464910										
CORRESPONDENCE DATA											
Fax Number:	(480)345-4100										
Phone:	(480) 899-3021										
Email:	info@patentaz.com										
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>											
Correspondent Name:	George D. Morgan										
Address Line 1:	4635 S. Lakeshore Dr., Suite 131										
Address Line 4:	Tempe, ARIZONA 85282										
ATTORNEY DOCKET NUMBER:	ASE2473										
NAME OF SUBMITTER:	George D. Morgan										
Total Attachments: 2 source=ASE2473Assignment#page1.tif source=ASE2473Assignment#page2.tif											

OP \$40.00 13464910

ASSIGNMENT OF APPLICATION

WHEREAS, We, Han-Chee Yen, 5F., No.5, Ln. 136, Mingde Rd., Beitou Dist., Taipei City 112, Taiwan (R.O.C.); Chi-Sheng Chung, No.118, Rongchang St., Nanzi Dist., Kaohsiung City 811, Taiwan (R.O.C.); Kuo-Hsien Liao, No.420, Fengshu W. St., Nantun Dist., Taichung City 408, Taiwan (R.O.C.); and Yung-I Yeh, No.22, Ln. 136, Hongchang St., Nanzi Dist., Kaohsiung City 811, Taiwan (R.O.C.) ("Assignors"), have an interest in the invention entitled "SEMICONDUCTOR PACKAGE INTEGRATED WITH CONFORMAL SHIELD AND ANTENNA" which is the subject of a United States application for patent entitled above; and

WHEREAS, Advanced Semiconductor Engineering, Inc., a corporation organized and existing under and by virtue of the laws of Taiwan R.O.C. with an address at No. 26, Chin 3rd Road, Nantze Export Processing Zone, Kaohsiung, Taiwan R.O.C. ("Assignee"), is desirous of acquiring Assignor's interest in the invention;

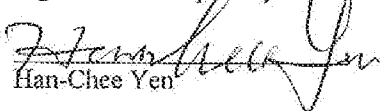
NOW THEREFORE, Assignor acknowledges receipt and adequacy of good and valuable consideration in exchange for this Assignment, and assigns to Assignee and its successors in interest, the full and exclusive right, title and interest to the invention described in the patent application listed above, in the United States of America and all foreign countries, including the right to claim priority under the laws of the United States, the Paris Convention, and any foreign countries, for the full term of the patent, including extensions of time, the same as if held by Assignor had this Assignment not been made.

Assignor covenants and agrees to cooperate with Assignee and execute all instruments or documents requested for the making and prosecution of any applications of any type for patent in the United States and in all foreign countries including, but not limited to the following: non-provisional utility, provisional, continuation, continuation-in-part, divisional, renewal or substitute, reissue, re-examination, or extension.

Assignor covenants and agrees to cooperate with Assignee in any litigation regarding the invention, patents or applications regarding the invention, including testifying for the benefit of Assignee.

Assignor covenants that no assignment, sale or agreement or encumbrance has been or will be entered into which would conflict with this Assignment.

Signed and Accepted by:


Han-Chee Yen

05/03/2012
Date

Chi-Sheng Chung

Date

Kuo-Hsien Liao

Date

Yung-I Yeh

Date

ASSIGNMENT OF APPLICATION

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Signed and Accepted by:

Han-Chee Yen

Date

Chi-Sheng Chung
Chi-Sheng Chung

2012-4-27
Date

Kuo-Hsien Liao
Kuo-Hsien Liao

2012-04-27
Date

Yung-I Yeh
Yung-I Yeh

2012-04-27
Date